

# INTERNATIONAL STANDARD



**Printed electronics –  
Part 202-5: Materials – Conductive ink – Mechanical bending test of a printed  
conductive layer on an insulating substrate**



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INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references .....	6
3 Terms and definitions .....	6
4 Standard environmental conditions .....	7
5 Test sample.....	7
5.1 General.....	7
5.2 Size of test sample .....	7
6 Testing method and test apparatus.....	8
6.1 General.....	8
6.2 Test apparatus.....	8
6.3 Test procedure.....	9
6.4 Measurement.....	10
7 Data analysis.....	11
7.1 Reporting the electrical properties .....	11
7.2 Report of the results .....	11
Annex A (normative) Stress state in bending deformation – Bending strain calculation .....	12
Annex B (informative) Damage area and electrical resistance change after sliding plate test.....	13
B.1 Damage area .....	13
B.2 Comparison of bending test methods .....	13
Bibliography.....	15
Figure 1 – Schematic diagram of mechanical test of printed film .....	8
Figure 2 – Apparatus for mechanical test of printed film .....	9
Figure A.1 – Bending strain and curvature relation in bent printed film .....	12
Figure A.2 – Schematic of outer bending and inner bending.....	12
Figure B.1 – Images of metal film after sliding test.....	13
Figure B.2 – Electrical resistance changes of sliding plate test and simple bending test .....	14
Table 1 – List of the size of the specimen .....	8
Table 2 – Combination of the effective sample length and the linear motion length .....	10
Table 3 – Resistance range of the test piece and the applied current.....	10

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## PRINTED ELECTRONICS –

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62899 series, published under the general title *Printed electronics*, can be found on the IEC website.

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## INTRODUCTION

The printing process is a highly promising technology for the fabrication of flexible devices. In particular, a printed conductive layer on an insulating substrate will be widely employed as an electrode or as an interconnect for flexible devices. It will be dealt with and commercialized as a type of composite material in which the conductive layer is formed on the substrate as a conductor.

For a conductive film, the electrical property under mechanical deformation is very important because it is highly sensitive to mechanical stress and degrades well before the mechanical fracture. Therefore, a method for evaluating the conductivity of film materials provided by suppliers, sometimes including an *in situ* measurement system, is required in the industry as these are the basic materials which will be used in printed devices. Although some bending tests already exist, it is necessary to consider the unique characteristics of the printed films that are fabricated on a polymer substrate, which is weak under high temperature. These films are operated under severe mechanical deformations, unlike the conventional Si- or glass-based conductive films.

In this document, a mechanical bending test is described to evaluate the electrical property of a printed conductive layer on a substrate under repeated mechanical deformations. This sliding plate test method can be available for practical application in the industry by enabling the long-term reliability testing of printed film.

## PRINTED ELECTRONICS –

### Part 202-5: Materials – Conductive ink – Mechanical bending test of a printed conductive layer on an insulating substrate

#### 1 Scope

This International Standard specifies a mechanical bending test for evaluating the electrical properties of a printed conductive layer on an insulating substrate under repeated mechanical deformation.

#### 2 Normative references

The following documents are referred to in the text in such a way that none or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62899-202:2016, *Printed electronics – Part 202: Materials – Conductive ink*

#### 3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

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- IEC Electropedia: available at <http://www.electropedia.org/>
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##### 3.1

##### **conductive material**

ingredient of a printing or coating material, which itself is electrically conductive or becomes electrically conductive by post treatment such as heating

[SOURCE: IEC-62899-202:2016, 3.1]

##### 3.2

##### **conductive ink**

fluid in which one or more small molecules, polymers, or particles are dissolved or dispersed, and which becomes an electrically conductive layer by post treatment such as heating

[SOURCE: IEC-62899-202:2016, 3.2]

##### 3.3

##### **conductive layer**

film-like electrically conductive body made of conductive ink, which is printed or coated on a substrate, followed as necessary by post treatment such as heating

[SOURCE: IEC-62899-202:2016, 3.3]